

PRIOR ART

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(71)Applicant : UNITIKA LTD

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(54) POLISHING PAD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a polishing pad which is capable of precisely polishing a semiconductor wafer and the like without contaminating or damaging the surface of the polished work.

SOLUTION: The polishing pad is mainly formed of composite materials composed of a resin matrix and inorganic materials displaying polishing properties. The composite materials are formed through an organic-inorganic hybrid synthesis method, and the inorganic materials are substantially, uniformly dispersed in the resin matrix. The inorganic materials are 10 nm or below in a grain diameter.